DOCUMENT CHANGE REQUEST

DCR number 1687

Changes required for: General

Originator: Stephan Hernandez

Date: 2024/09/12

Date sent: 2024/09/11

Organisation: ESTEC

Status: IMPLEMENTED

Title:	REP008		
Number:	REP008	Issue:	13

Other documents affected:

Page:

-

Paragraph:

-

Original wording:

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Proposed wording:

New:

390, Alter Technology TÜV Nord, Scotland
Assembly and testing processes of Hermetically Encapsulated Integrated Circuits: Epoxy attached, wire bonded SiGe IC in hermetic LGA/BGA ceramic package.

Justification:

Publication PCAL September 2024

Attachments:
N/A
Modifications:
N/A
Approval signature:
Date signed:
2024-09-12